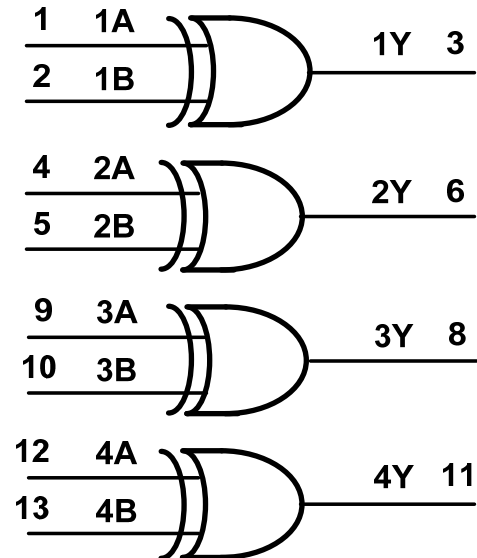


## Pin Descriptions

Pin Number	Pin Name	Description
1	1A	Data Input
2	1B	Data Input
3	1Y	Data Output
4	2A	Data Input
5	2B	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3B	Data Input
11	4Y	Data Output
12	4A	Data Input
13	4B	Data Input
14	Vcc	Supply Voltage

## Logic Diagram



## Function Table

Inputs		Output
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

## Absolute Maximum Ratings (Note 4)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 7.0	V
V <sub>I</sub>	Input Voltage Range note 4	-0.5 to 7.0	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0V	-20	mA
I <sub>OK</sub>	Output Clamp Current V <sub>O</sub> < -0V	-50	mA
I <sub>O</sub>	Continuous Output Current - 0.5V < V <sub>O</sub> < V <sub>CC</sub> + 0.5V	+/- 25	mA
I <sub>CC</sub>	Continuous Current Through Vcc	50	mA
I <sub>GND</sub>	Continuous Current Through GND	-50	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to 150	°C
T <sub>STG</sub>	Storage Temperature	-65 to 150	°C
P <sub>TOT</sub>	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

**Recommended Operating Conditions** (Note 5)

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage	–	2.0	5.5	V
V <sub>I</sub>	Input Voltage	–	0	5.5	V
V <sub>O</sub>	Output Voltage	–	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-Level Output Current	2.0V	–	-50	mA
		2.3V to 2.7V	–	-2	μA
		3.0V to 3.6V	–	-6	mA
		4.5V to 5.5V	–	-12	mA
I <sub>OL</sub>	Low-Level Output Current	2.0V	–	50	μA
		2.3V to 2.7V	–	2	mA
		3.0V to 3.6V	–	6	mA
		4.5V to 5.5V	–	12	mA
Δt/ΔV	Input Transition Rise or Fall Rate	2.3V to 2.7V	–	200	ns/V
		3.0V to 3.6V	–	100	
		4.5V to 5.5V	–	20	
T <sub>A</sub>	Operating Free-Air Temperature	–	-40	+125	°C

Note: 5. Unused inputs should be held at V<sub>CC</sub> or Ground.

**Electrical Characteristics**

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	T <sub>A</sub> = -40 to +85°C		T <sub>A</sub> = -40 to +125°C		Unit
				Min	Max	Min	Max	
V <sub>IH</sub>	High-Level Input Voltage	–	2.0V	1.5	–	1.5	–	V
		–	2.3V to 2.7V	V <sub>CC</sub> X 0.7	–	V <sub>CC</sub> X 0.7	–	
		–	3.0V to 3.6V	V <sub>CC</sub> X 0.7	–	V <sub>CC</sub> X 0.7	–	
		–	4.5V to 5.5V	V <sub>CC</sub> X 0.7	–	V <sub>CC</sub> X 0.7	–	–
V <sub>IL</sub>	Low-Level Input Voltage	–	2.0V	–	0.5	–	0.5	V
		–	2.3V to 2.7V	–	V <sub>CC</sub> X 0.3	–	V <sub>CC</sub> X 0.3	
		–	3.0V to 3.6V	–	V <sub>CC</sub> X 0.3	–	V <sub>CC</sub> X 0.3	
		–	4.5V to 5.5V	–	V <sub>CC</sub> X 0.3	–	V <sub>CC</sub> X 0.3	–
V <sub>OH</sub>	High-Level Output Voltage	I <sub>OH</sub> = -50μA	2.0V to 5.5V	V <sub>CC</sub> -0.1	–	V <sub>CC</sub> -0.1	–	V
		I <sub>OH</sub> = -2mA	2.3V	2.0	–	2.0	–	
		I <sub>OH</sub> = -6mA	3.0V	2.48	–	2.48	–	
		I <sub>OH</sub> = -12mA	4.5V	3.8	–	3.8	–	
V <sub>OL</sub>	Low-Level Output Voltage	I <sub>OL</sub> = 50μA	2.0V to 5.5V	–	0.1	–	0.1	V
		I <sub>OL</sub> = 2mA	2.3V	–	0.4	–	0.4	
		I <sub>OL</sub> = 6mA	3.0V	–	0.44	–	0.44	
		I <sub>OL</sub> = 12mA	4.5V	–	0.55	–	0.55	
I <sub>OFF</sub>	Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5V	0V	–	5	–	5	μA
I <sub>I</sub>	Input Current	V <sub>I</sub> = GND or 5.5V	0 to 5.5V	–	±1	–	±1	μA
I <sub>CC</sub>	Supply Current	V <sub>I</sub> = GND or V <sub>CC</sub> I <sub>O</sub> = 0	5.5V	–	20	–	20	μA

## Switching Characteristics

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	T <sub>A</sub> = +25°C			-40 to +85°C		-40 to +125°C		Unit
				Min	Typ.	Max	Min	Max	Min	Max	
t <sub>PD</sub>	Propagation Delay A <sub>N</sub> to Y <sub>N</sub>	Figure 1 C <sub>L</sub> =15pF	2.5V ± 0.2V	-	7.9	17.6	1	21	1	22	ns
			3.3V ± 0.3V	-	5.5	11	1	13	1	14	
			5.0V ± 0.5V	-	3.7	6.8	1	8	1	9	
		Figure 1 C <sub>L</sub> =50 pF	2.5V ± 0.2V	-	10.5	22.6	1	26.5	1	27.5	ns
			3.3V ± 0.3V	-	7.4	14.5	1	16.5	1	17.5	
			5.0V ± 0.5V	-	5.3	8.8	1	10	1	11	

## Operating Characteristics

 T<sub>A</sub> = +25°C

Parameter		Test Conditions	V <sub>CC</sub>	TYP	Unit
C <sub>pd</sub>	Power Dissipation Capacitance per Gate	F = 10MHz C <sub>L</sub> = 50pF	3.3V	8.4	pF
			5.0V	8.8	

## Noise Characteristics

 V<sub>CC</sub> = 3V, C<sub>L</sub> = 50pF T<sub>A</sub> = +25°C

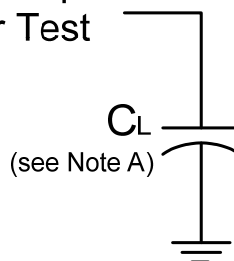
Symbol	Parameter	Min	Typ.	Max	Unit
V <sub>OL(p)</sub>	Quiet output, maximum dynamic V <sub>OL</sub>	-	0.2	0.8	V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>	-	-0.1	-0.8	V
V <sub>OH(V)</sub>	Quiet output, minimum dynamic V <sub>OH</sub>	-	3.1	-	V
V <sub>IH(D)</sub>	High Level dynamic input voltage	2.31	-	-	V
V <sub>IL(D)</sub>	Low Level dynamic input voltage	-	-	0.99	V

## Package Characteristics

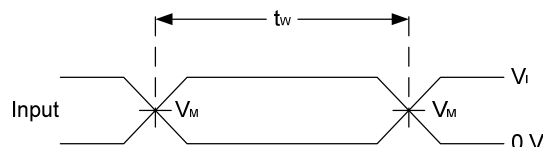
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	Min	Typ.	Max	Unit
C <sub>i</sub>	Input Capacitance	V <sub>i</sub> = V <sub>CC</sub> – or GND	2.0 to 5.5V	-	3.3	10	pF

## Parameter Measurement Information

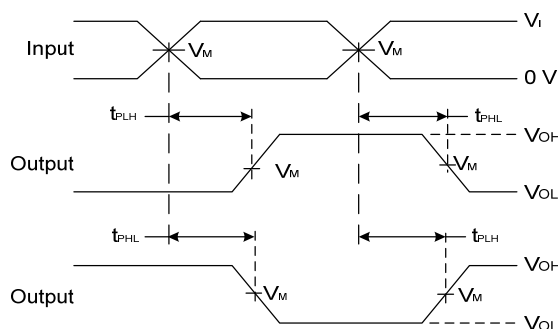
From Output  
Under Test



$V_{CC}$	Inputs		$V_M$	$C_L$
	$V_I$	$t_r/t_f$		
2.0V to 5.5V	$V_{CC}$	<3ns	$V_{CC}/2$	15pF or 50pF



**Voltage Waveform  
Pulse Duration**

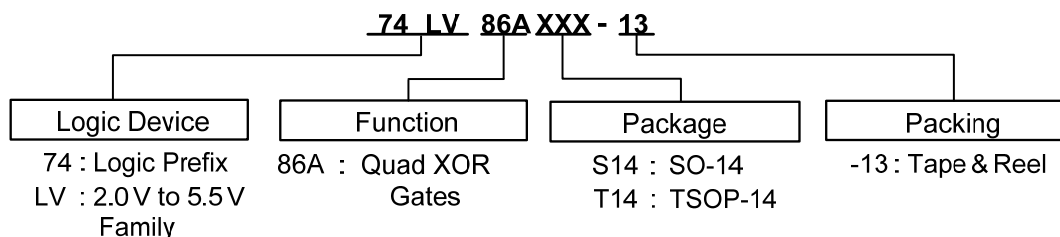


**Voltage Waveform  
Propagation Delay Times  
Inverting and Non Inverting Outputs**

- Notes:
- A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate  $\leq 10\text{MHz}$
  - C. Inputs are measured separately one transition per measurement
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$

**Figure 1. Load Circuit and Voltage Waveforms**

## Ordering Information

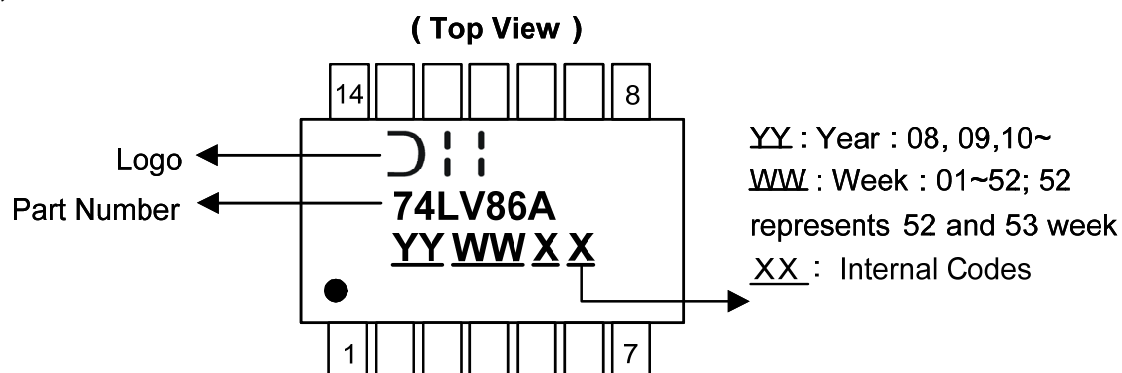


Device	Package Code	Packaging (Note 6)	13" Tape and Reel	
			Quantity	Part Number Suffix
74LV86AS14-13	S14	SO-14	2500/Tape & Reel	-13
74LV86AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Note: 6. The taping orientation and tape details can be found at <http://www.diodes.com/datasheets/ap02007.pdf>

## Marking Information

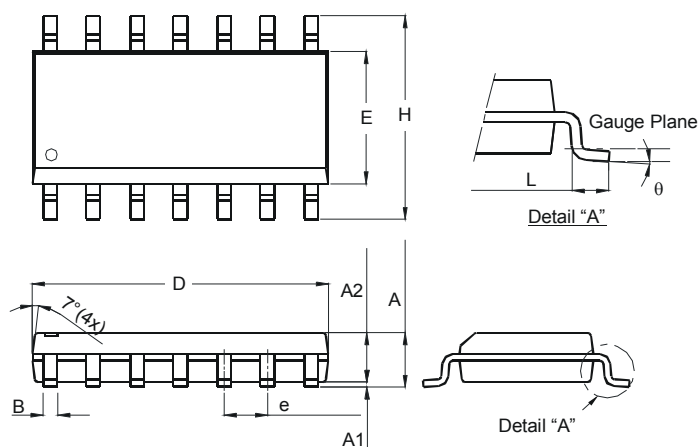
### (1) SO14, TSSOP14



Part Number	Package
74LV86AS14	SO-14
74LV86AT14	TSSOP-14

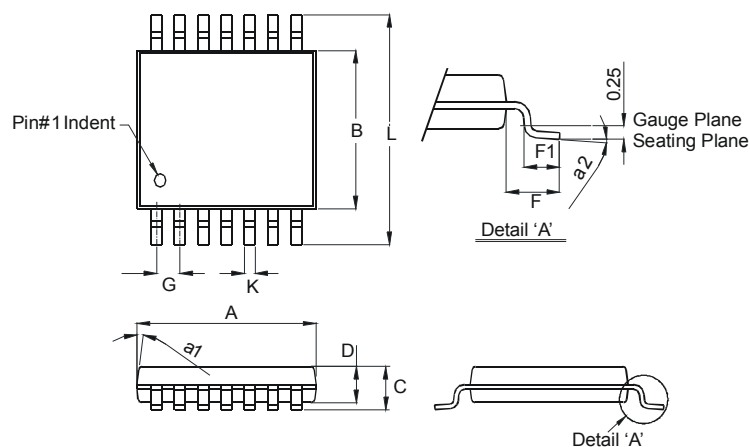
# Package Outline Dimensions (All Dimensions in mm)

## Package Type: SO-14



SO-14		
Dim	Min	Max
A	1.47	1.73
A1	0.10	0.25
A2	1.45 Typ	
B	0.33	0.51
D	8.53	8.74
E	3.80	3.99
e	1.27 Typ	
H	5.80	6.20
L	0.38	1.27
$\theta$	0°	8°
All Dimensions in mm		

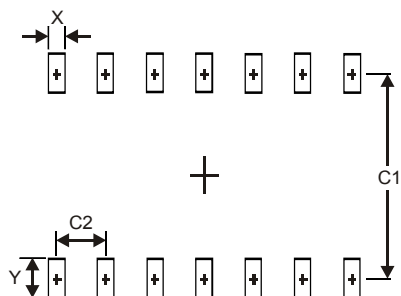
## Package Type: TSSOP-14



TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
A	4.9	5.10
B	4.30	4.50
C	—	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

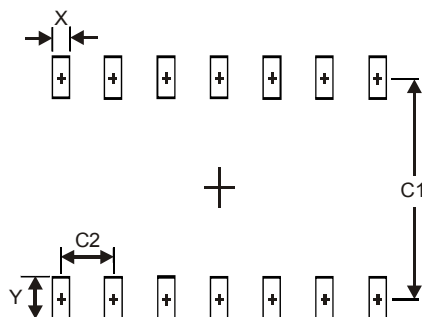
## Suggested Pad Layout

Package Type: SO-14



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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